N-Channel Power MOSFET 500 V, 0.85 Ω

Features

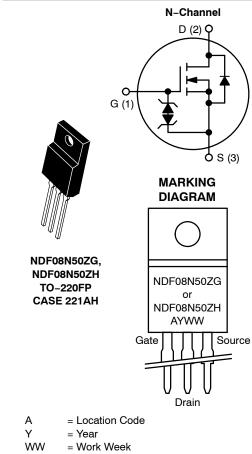
- Low ON Resistance
- Low Gate Charge
- ESD Diode-Protected Gate
- 100% Avalanche Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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V _{DSS}	R _{DS(ON)} (MAX) @ 3.6 A
500 V	0.85 Ω



G, H = Pb-Free, Halogen-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NDF08N50ZG	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail
NDF08N50ZH	TO-220FP (Pb-Free, Halogen-Free)	50 Units / Rail

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	NDF08N50Z	Unit
Drain-to-Source Voltage	V _{DSS}	500	V
Continuous Drain Current $R_{\theta JC}$ (Note 1)	Ι _D	8.5	А
Continuous Drain Current $R_{\theta JC}$ T _A = 100°C (Note 1)	Ι _D	5.4	A
Pulsed Drain Current, V _{GS} @ 10 V	I _{DM}	34	A
Power Dissipation	PD	35	W
Gate-to-Source Voltage	V _{GS}	±30	V
Single Pulse Avalanche Energy, $I_D = 7.5 \text{ A}$	E _{AS}	190	mJ
ESD (HBM) (JESD 22–A114)	V _{esd}	3500	V
$\label{eq:RMS} \begin{array}{l} \text{RMS Isolation Voltage} \\ (t=0.3 \; \text{sec.}, \; \text{R.H.} \leq 30\%, \\ T_{\text{A}} = 25^{\circ}\text{C}) \; (\text{Figure 14}) \end{array}$	V _{ISO}	4500	V
Peak Diode Recovery (Note 2)	dV/dt	4.5	V/ns
MOSFET dV/dt	dV/dt	60	V/ns
Continuous Source Current (Body Diode)	I _S	7.5	A
Maximum Temperature for Soldering Leads	ΤL	260	°C
Operating Junction and Storage Temperature Range	T _J , T _{stg}	–55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Limited by maximum junction temperature

2. I_{SD} = 7.5 Å, di/dt \leq 100 Å/ $\mu s,$ V_{DD} \leq $BV_{DSS},$ T_{J} = +150°C

THERMAL RESISTANCE

Parameter	Symbol	NDF08N50Z	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	3.6	°C/W
Junction-to-Ambient Steady State (Note 3)	$R_{\theta JA}$	50	

3. Insertion mounted

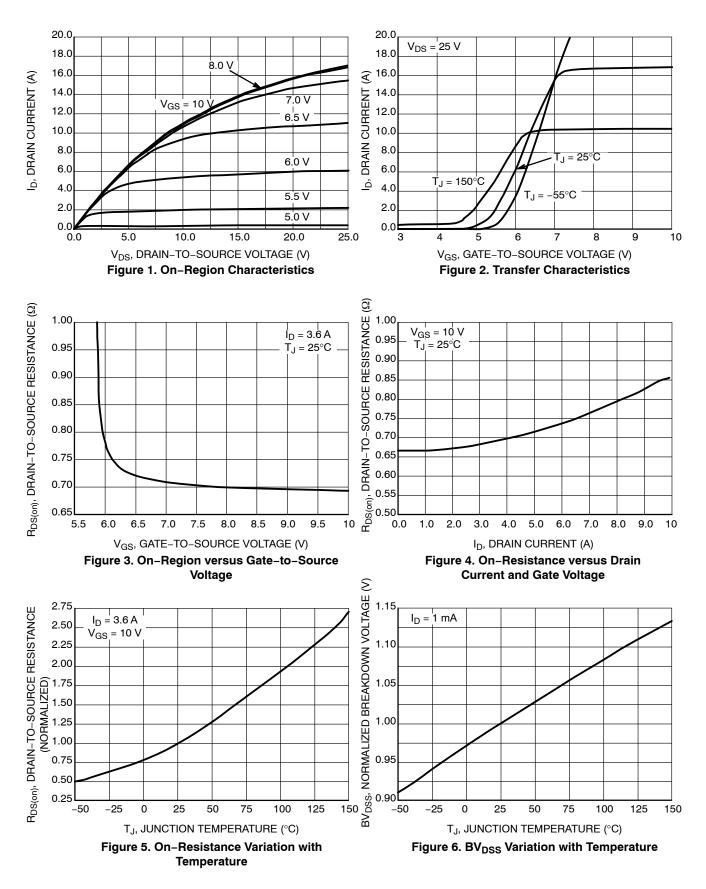
ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise noted)

Characteristic	Test Conditions		Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS			-		-	-	-	
Drain-to-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1 mA		BV _{DSS}	500			V	
Breakdown Voltage Temperature Co- efficient	Reference to 25°C, $I_D = 1 \text{ mA}$		$\Delta BV_{DSS}/\Delta T_J$		0.6		V/°C	
Drain-to-Source Leakage Current		25°C	I _{DSS}			1	μA	
	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	150°C				50	1	
Gate-to-Source Forward Leakage	V _{GS} = ±20 V		I _{GSS}			±10	μA	
ON CHARACTERISTICS (Note 4)			•		-	•		
Static Drain-to-Source On-Resistance	V _{GS} = 10 V, I _D = 3.6 A	4	R _{DS(on)}		0.69	0.85	Ω	
Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 100 \ \mu$	A	V _{GS(th)}	3.0	3.9	4.5	V	
Forward Transconductance	V _{DS} = 15 V, I _D = 3.75	A	9fs		6.0		S	
DYNAMIC CHARACTERISTICS							-	
Input Capacitance (Note 5)			C _{iss}	730	912	1095	pF	
Output Capacitance (Note 5)	$V_{DS} = 25 V, V_{GS} = 0 V$	Ι,	C _{oss}	95	120	140		
Reverse Transfer Capacitance (Note 5)	f = 1.0 MHz		C _{rss}	15	27	35		
Total Gate Charge (Note 5)			Qg	16	31	46	nC	
Gate-to-Source Charge (Note 5)			Q _{gs}	3	6.2	9		
Gate-to-Drain ("Miller") Charge (Note 5)	$V_{DD} = 250 \text{ V}, \text{ I}_{D} = 7.5 \text{ A}, \ V_{GS} = 10 \text{ V}$		Q _{gd}	8	17	25		
Plateau Voltage			V _{GP}		6.3		V	
Gate Resistance			R _g		3.0		Ω	
RESISTIVE SWITCHING CHARACTER	RISTICS							
Turn-On Delay Time			t _{d(on)}		13		ns	
Rise Time	V _{DD} = 250 V, I _D = 7.5 /	۹,	t _r		23		1	
Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{G} = 5 \Omega$	2	t _{d(off)}		31			
Fall Time			t _f		29			
SOURCE-DRAIN DIODE CHARACTE	RISTICS (T _C = 25°C unless oth	nerwise no	ted)		•			
			,		1	1		

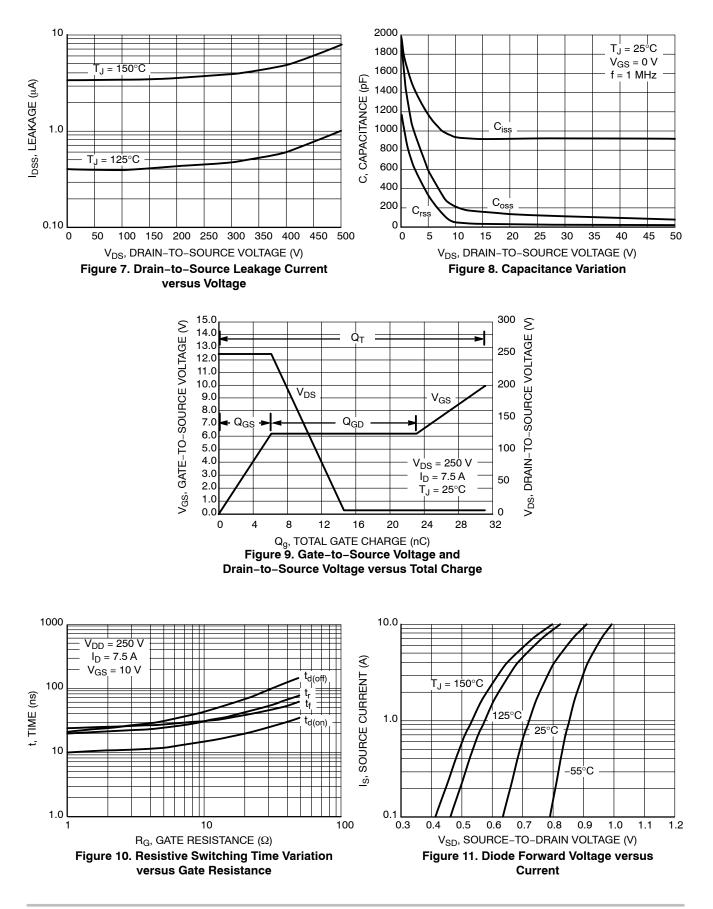
Diode Forward Voltage	$I_{\rm S}$ = 7.5 A, $V_{\rm GS}$ = 0 V	V _{SD}		1.6	V
Reverse Recovery Time	V _{GS} = 0 V, V _{DD} = 30 V	t _{rr}	295		ns
Reverse Recovery Charge	I _S = 7.5 A, di/dt = 100 A/μs	Q _{rr}	1.85		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Pulse Width ≤ 380 µs, Duty Cycle ≤ 2%.
5. Guaranteed by design.

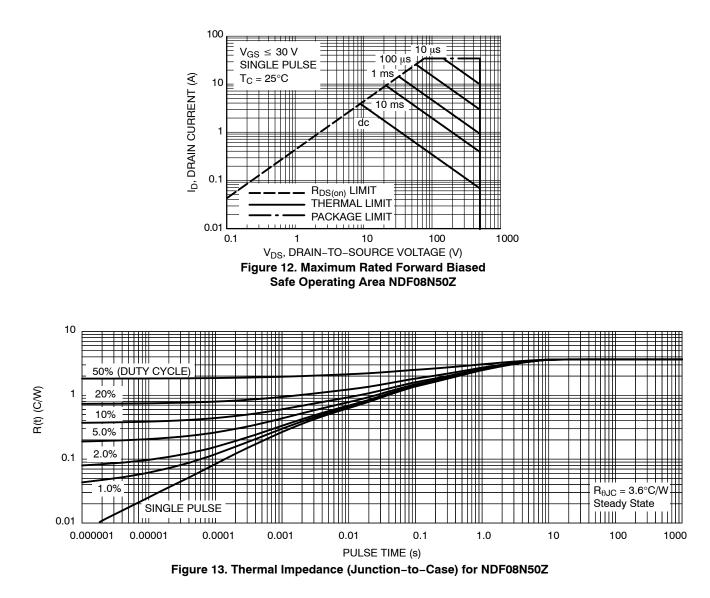
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



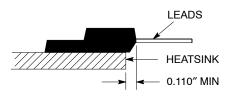


Figure 14. Isolation Test Diagram

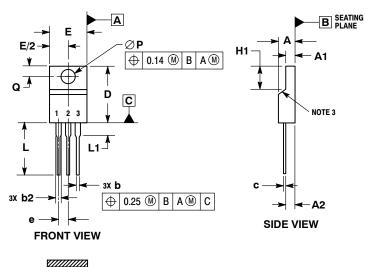
Measurement made between leads and heatsink with all leads shorted together.

*For additional mounting information, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TO-220 FULLPACK, 3-LEAD CASE 221AH

ISSUE F

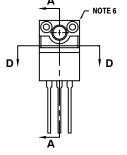


NOTES: DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- 2. CONTROLLING DIMENSION: MILLIMETERS. 3. CONTOUR UNCONTROLLED IN THIS AREA.
- 4
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.
- CONTOURS AND FEATURES OF THE MOLDED PACKAGE BODY
- MAY VARY WITHIN THE ENVELOP DEFINED BY DIMENSIONS A1 AND H1 FOR MANUFACTURING PURPOSES.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.30	4.70	
A1	2.50	2.90	
A2	2.50	2.90	
b	0.54	0.84	
b2	1.10	1.40	
C	0.49	0.79	
D	14.70	15.30	
Е	9.70	10.30	
е	2.54 BSC		
H1	6.60	7.10	
L	12.50	14.73	
L1		2.80	
Ρ	3.00	3.40	
Q	2.80	3.20	





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